

Product / Process Change Notification



N° 2020-086-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Introduction of an Additional Assembly And Final Test Location at HANA Semiconductor (Ayutthaya, Thailand) Co., Ltd. for dedicated SOIC Products in PG-DSO-8/14

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **26. August 2020**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates: “**Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
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Chairman of the Supervisory Board: Dr. Wolfgang Eder
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider
Registered Office: Neubiberg
Commercial Register: München HRB 126492

Product / Process Change Notification



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■ **Products affected:** Please refer to attached affected product list 1_cip20086_a

■ **Detailed Change Information:**

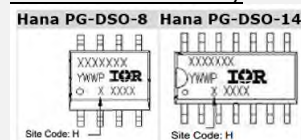
Subject: Introduction of an Additional Assembly And Final Test Location at HANA Semiconductor (Ayutthaya, Thailand) Co., Ltd. for dedicated SOIC Products in PG-DSO-8/14

Reason: Expansion of assembly and test capacity to cover increasing customer demand, and enable flexible manufacturing.

Description: Old New

- Refer to 3_cip20086_a

■ **Product Identification:** Internal traceability via Baunumber, Lotnumber and marking on device
External traceability via the marking on device



■ **Impact of Change:**

- **NO** change on electrical, thermal parameters and reliability as proven via product qualification and characterization.
- **NO** change in package outline dimensions.
- **NO** change of existing Infineon specifications and datasheet parameters

■ **Attachments:** 1_cip20086_a : Affected product list
3_cip20086_a: Customer Information Package

■ **Time Schedule:**

- Final qualification report: available
- First samples available: on request
- Intended start of delivery: Oct'20 or earlier depending on customer approval

If you have any questions, please do not hesitate to contact your local Sales office.

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Sales name	SP number	OPN	Package
IR11452STRPBF	SP001562676	IR11452STRPBF	PG-DSO-8
IR1153STRPBF	SP001550848	IR1153STRPBF	PG-DSO-8
IR1155STRPBF	SP001574334	IR1155STRPBF	PG-DSO-8
IR11682STRPBF	SP001553776	IR11682STRPBF	PG-DSO-8
IR11688STRPBF	SP001561330	IR11688STRPBF	PG-DSO-8
IRS2548DSTRPBF	SP001577258	IRS2548DSTRPBF	PG-DSO-14
IRS2982STRPBF	SP001569856	IRS2982STRPBF	PG-DSO-8